

REMARKS

Claims 1, 2, 4 through 10 and 12 through 15 are currently pending in the application.

This amendment is in response to the Office Action of January 2, 2004.

**Information Disclosure Statement(s)**

Applicants note the filing of an Information Disclosure Statement herein on August 4, 2003 and note that a copy of the PTO-1449 was not returned with the outstanding Office Action. Applicants respectfully request that the information cited on the PTO-1449 (which is the same as that of record to that date in the parent application hereto) be made of record herein.

**35 U.S.C. § 102(e) Anticipation Rejections**

Anticipation Rejection Based on Beng et al. (U.S. Patent 5,563,443)

Claims 1, 2, 5 through 10 and 12 through 15 are rejected under 35 U.S.C. § 102(e) as being anticipated by Beng et al.

Applicants assert that a claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference.

*Verdegaal Brothers v. Union Oil Co. of California*, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989).

After carefully considering the cited prior art, the rejections, and the Examiner's comments, Applicants have amended the claimed invention of claim 1 to clearly distinguish over the cited prior art.

Turning to the Beng et al. reference, a packaged integrated circuit includes a lead frame adhesively attached to the active surface of the semiconductor IC chip. The lead fingers extend over the active surface with the ends of the lead fingers terminating adjacent a row of bond pads located on the active surface of the semiconductor IC chip. The Beng et al. reference does not describe any lead frame having an opening for a semiconductor device formed by the ends of the lead fingers. At best, the Beng et al. reference describes a lead frame having lead fingers having

the ends thereof forming an opening for a row of bond pads located on the active surface of a semiconductor IC chip.

Applicants assert that the Beng et al reference does not and cannot anticipate the presently claimed inventions of presently amended independent claim 1 and pending independent claim 5 because the Beng et al. reference does not identically describe each and every element of Applicants claimed inventions in as complete detail as is contained in such claims. For instance, the Beng et al. reference does not identically describe in the same detail as is contained in the claims the elements of the claimed inventions of independent claims 1 and 5 calling for “a plurality of lead fingers of the lead frame, each lead finger of the plurality having an end, at least a portion of the plurality of lead fingers having an opening for locating a semiconductor device therein having said plurality of lead fingers located adjacent the sides of the semiconductor device”, “at least one bus bar having a portion extending along the end of the at least one lead finger of the plurality of lead fingers and along a portion of one side of a semiconductor device when located in said opening”, and “a lead frame located adjacent another lead frame of a plurality of lead frames having an opening therebetween, the lead frame having a plurality of inwardly extending leads extending to an opening for a semiconductor device to be located therein, at least one lead of the plurality of inwardly extending leads having a portion extending along at least a portion of a length of at least two adjacent portions of the periphery of a semiconductor device and extending between the semiconductor device and another lead of the plurality of inwardly extending leads and a second inwardly extending lead extending along another portion of the length of the at least two adjacent portions of the periphery of a semiconductor device, the at least one lead of the plurality of inwardly extending leads for electrically connecting a semiconductor device to a power source”.

In contrast to the inventions of independent claims 1 and 5, Beng et al. describes a lead frame having the lead fingers thereof adhesively attached to the active surface of a semiconductor IC chip with the ends of the lead fingers located adjacent a row of bond pads located, in turn, on the active surface of the semiconductor IC chip with the lead fingers extending thereover. Clearly, such is not the claimed inventions of independent claims 1 and 5.

Therefore, the Beng et al. reference cannot and does not anticipate the claimed inventions of independent claims 1 and 5 as well as dependent claims 2, 3 and 6 through 10, and 12 through 15 therefrom.

**Allowable Subject Matter**

Applicants note with appreciation the allowance of claim 4.

Applicants submit that claims 1, 2, 4 through 10 and 12 through 15 are clearly allowable over the cited prior art.

Applicants request the allowance of claims 1, 2, 4 through 10 and 12 through 15 and the case passed for issue.

Respectfully submitted,



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